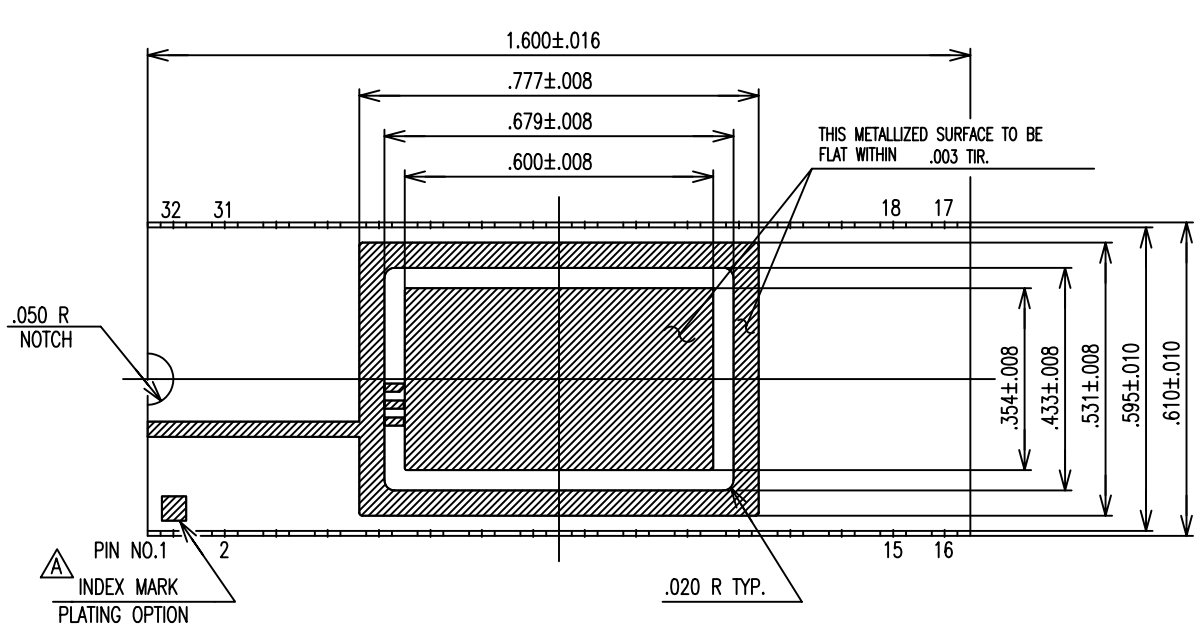

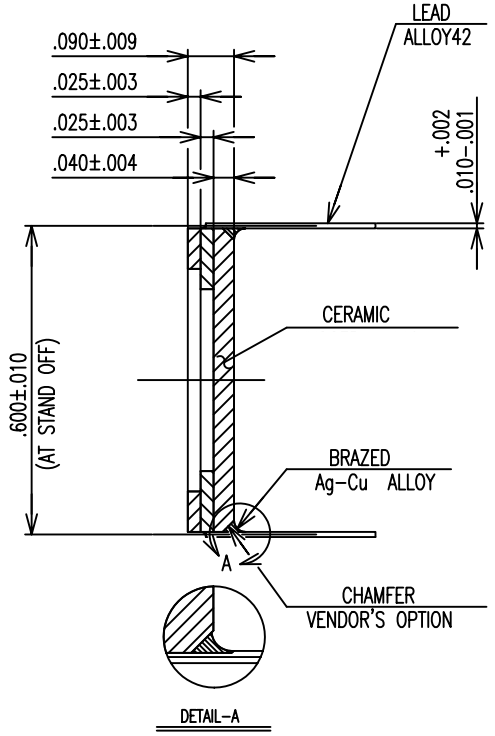

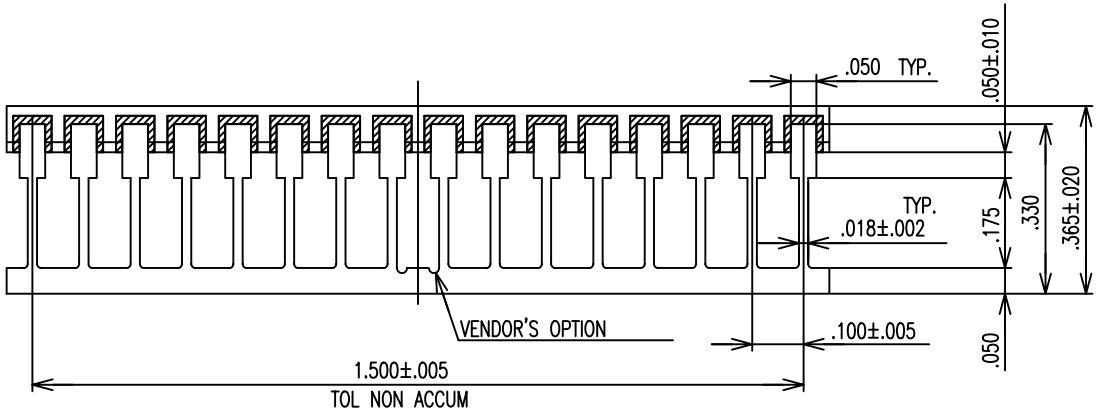

NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.600HM MAX.

MODIFICATION						32 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
								M.	T.C/		MAY.22.'95
						SCALE 4/1	MATEP AS INDICATED	±.005 THIRD ANGLE PROJECTION			
A	CHANGED:INDEX MARK	JUN.07.'95	M.SU	T.C/S.F	T.A			DRAWING NO.			
	CHANGED	DATE	DRAWN	CHECKED	APPROVED						